

.200" (5,08mm) POWER SOCKETS HPF SERIES

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPF

Insulator Material: Black LCP

Contact Material: BeCu

Plating: Sn over 50µ" (1,27µm) Ni
Insertion Depth: (3,68mm) .145" to (8,26mm) .325" (.368" (9,35mm) plus board thickness minimum for bottom entry)

Wiping Distance: (0,38mm) .015"

Insertion Force: (Single contact only) 56oz (15,57N) avg.

Withdrawal Force: (Single contact only) 52oz (14,46N) avg.

Max Processing Temp: 230°C for 60 seconds, or 260°C for 20 seconds 3x

Lead-Free Solderable: Yes

SMT Lead Coplanarity: (0,15mm) .006" max (02-10) (0,20mm) .008" max (11-20)

RoHS Compliant: Yes

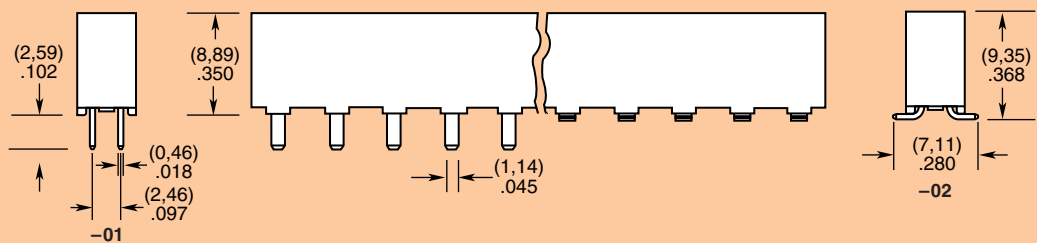
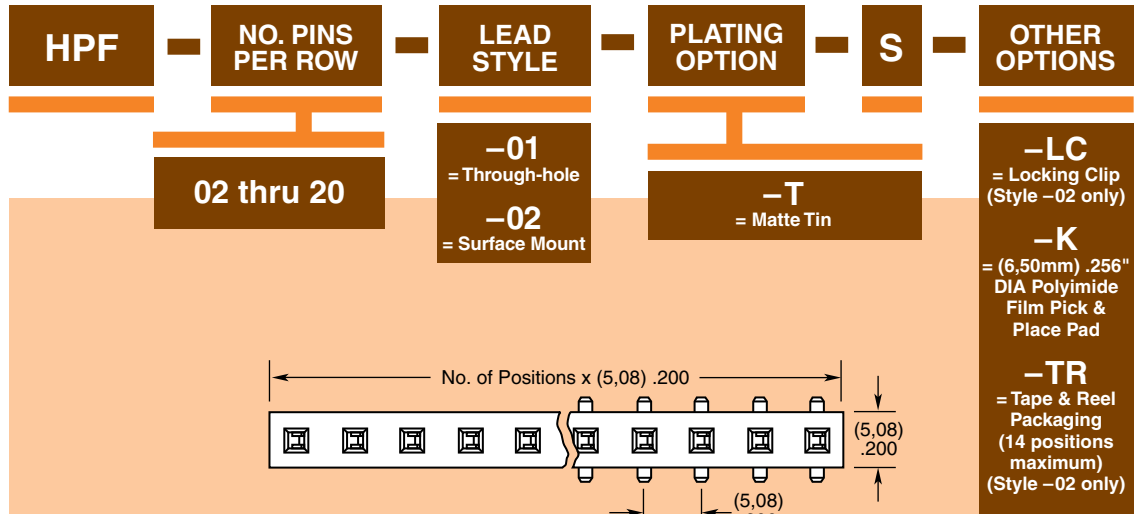
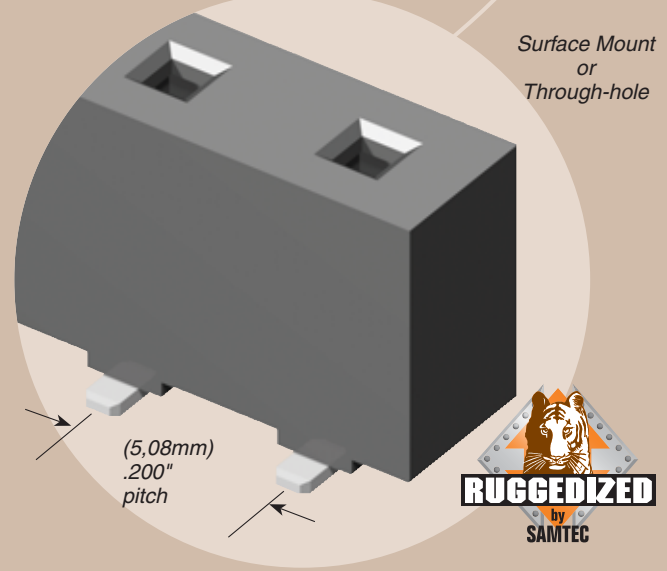
Mates with: HPM, HPW

POWER EYE CONTACT



CURRENT RATING	
AMBIENT TEMP	HPM/HPF
20°C	13A
40°C	11.8A
60°C	10A
75°C	8A

6 POSITIONS POWERED



Note: Some lengths, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

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